



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et. al.

Serial No.: 10/624,833

Filed: July 22, 2003

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING AND DEVICES
RESULTING THEREFROM

Confirmation No.: Unknown

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 2269-3572.2US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

October 16, 2003
Date

Signature

Leah J. Barrow
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 4 of this paper.

Remarks begin on page 8 of this paper.